

# MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet

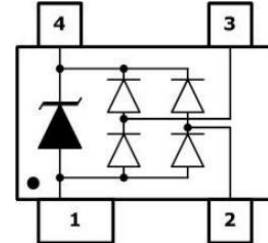
## Features

- Ultra low leakage: nA level
- Operating voltage: 5V
- Low clamping voltage
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test  
Air discharge: ±15kV  
Contact discharge: ±8kV
  - IEC61000-4-4 (EFT) 40A (5/50ns)
  - IEC61000-4-5 (Lightning) 3A (8/20µs)
- RoHS Compliant

## Applications

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)
- Notebook Computers
- SIM Ports
- 10/100 Ethernet

## Pin Configuration



## SOT-143

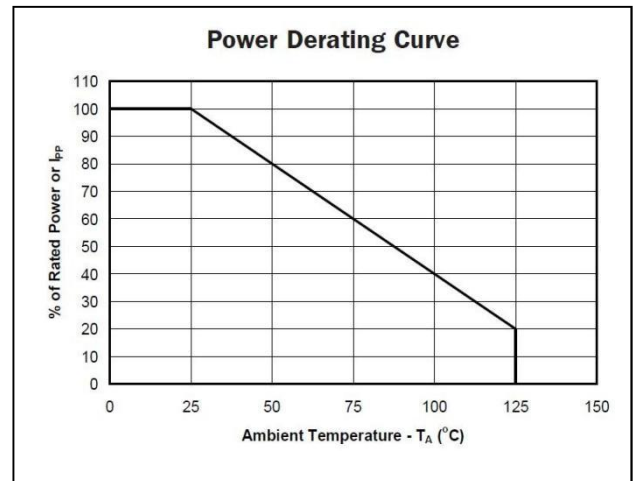
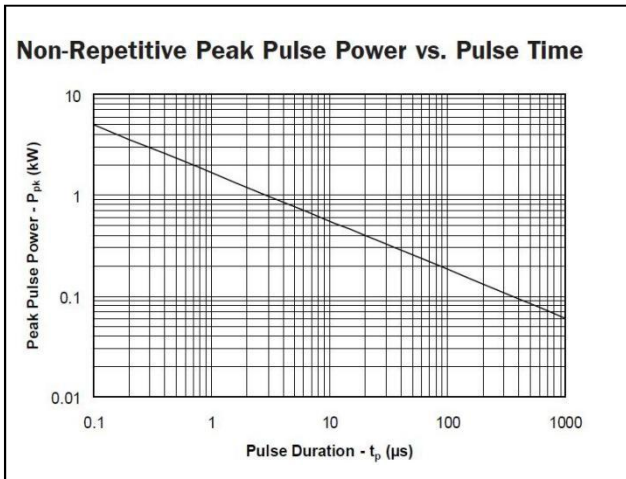
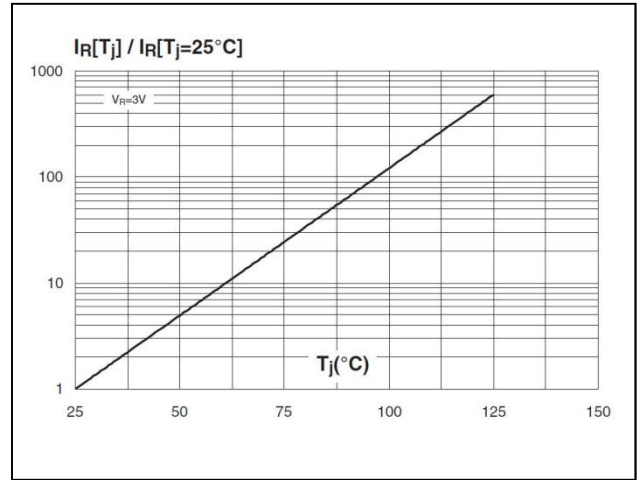
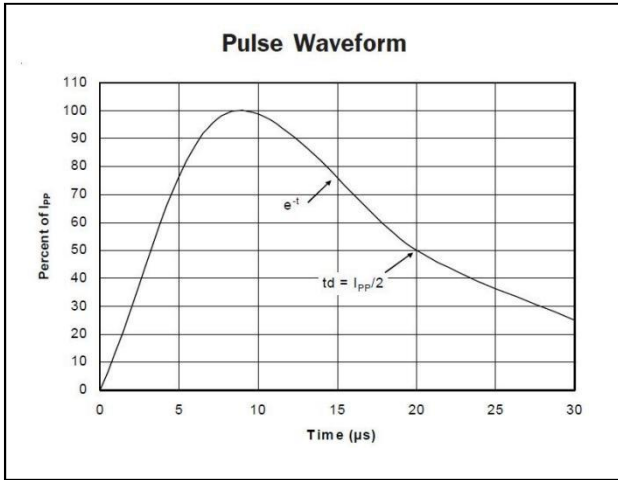
## Electrical Characteristics (TA=25°C unless otherwise specified)

P/N	V <sub>RWM</sub> (V)	V <sub>BR</sub> (V)	I <sub>T</sub> (mA)	V <sub>C</sub> @1A	V <sub>C</sub>		I <sub>R</sub> µA (Max)	C (Pf) (Typ.)
					(Max)	(@A)		
MSR05	5	6	1	9.8	23	3	1	1.2

## Absolute Maximum Ratings (T<sub>amb</sub>=25°C unless otherwise specified)

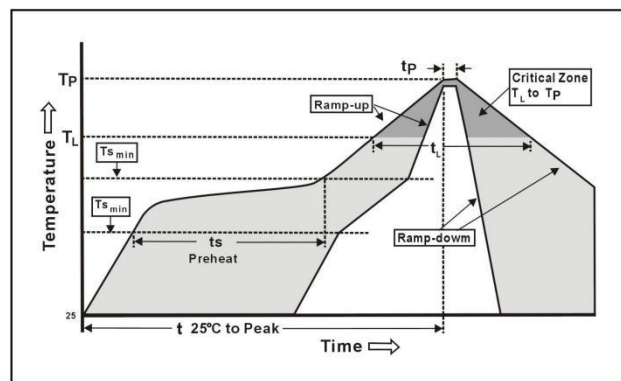
Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20µs)	P <sub>pp</sub>	300	W
ESD per IEC 61000-4-2 (Air)	V <sub>ESD</sub>	± 15	Kv
ESD per IEC 61000-4-2 (Contact)		± 8	
Operating Temperature Range	T <sub>J</sub>	-55 to +125	°C
Storage Temperature Range	T <sub>STJ</sub>	-55 to +150	°C

Typical Characteristics @  $T_a=25^\circ\text{C}$  unless otherwise specified

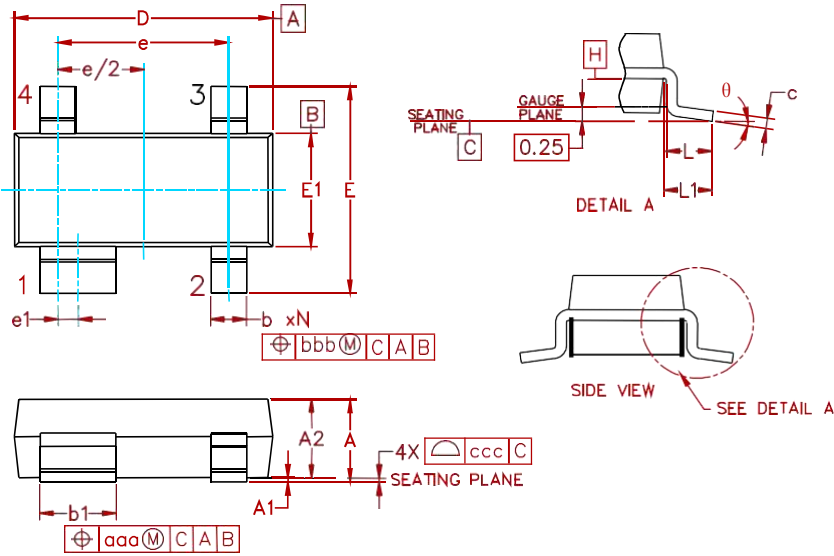


Soldering Parameters

Reflow Condition		Fb – Free assembly
Pre Heat	- Temperature Min ( $T_{s(\text{Min})}$ )	150°C
	- Temperature Max ( $T_{s(\text{Max})}$ )	200°C
	- Time (Min to max) ( $t_s$ )	60 – 180 secs
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3°C/second Max
$T_{s(\text{Max})}$ to $T_L$ - Ramp-up Rate		3°C/second Max
Reflow	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Temperature ( $t_l$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )		250 $^{+0.5}$ °C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		6°C/second Max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes Max.
Do not exceed		260°C

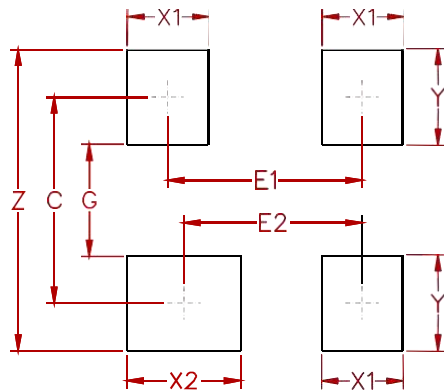


**PACKAGE MECHANICAL DATA**



Symbol	Inches			Millimeters		
	Min.	Nom.	Max.	Min.	Nom.	Max.
<b>A</b>	0.031	-	0.048	0.80	-	1.22
<b>A1</b>	0.000	-	0.008	0.013	-	0.15
<b>A2</b>	0.020	0.035	0.042	0.75	0.90	1.07
<b>b</b>	0.011	-	0.020	0.30	-	0.51
<b>b1</b>	0.029	-	0.037	0.76	-	0.94
<b>c</b>	0.003	-	0.008	0.08	-	0.20
<b>D</b>	0.110	0.114	0.120	2.80	2.90	3.04
<b>E</b>	0.082	0.093	0.104	2.10	2.37	2.64
<b>E1</b>	0.047	0.051	0.055	1.20	1.30	1.40
<b>e</b>	0.075			1.92 BSC		
<b>e1</b>	0.008			0.20 BSC		
<b>L</b>	0.015	0.020	0.024	0.40	0.50	0.60
<b>L1</b>	(0.021)			(0.54)		
<b>N</b>	4			4		
<b>θ</b>	0°	-	8°	0°	-	8°
<b>aaa</b>	0.006			0.15		
<b>bbb</b>	0.008			0.20		
<b>ccc</b>	0.004			0.10		

**Suggested Pad Layout**



**REEL SPECIFICATION**

P/N	PKG	QTY
MSR05	SOT-143	3000

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